

## PRODUCT CHANGE NOTICE

PCN Number:	2018-BLC-03 Rev 2	Issue Date:	10/7/19
PCN Type:	<input checked="" type="checkbox"/> Product/Process Change <input type="checkbox"/> Discontinued Product		

**Part Number(s) Affected:** KFAXX.00-XSMT[F]

### Description of the Change:

KFAXX.00XSMT series of products will change from thick film solderable gold terminals to thick film nickel barrier solder plated Sn60Pb40 terminals.

KFAXX.00XSMTF series of products will change from thick film solderable gold terminals to thick film nickel barrier silver plated RoHS compliant terminals.

In addition, both product series will have ground terminals that extend to the edge of the chip as shown in Figure 2. The protective coating will also be extended to cover a larger area of the circuit. The input/output terminals will also be extended to the edge of the chip providing an enlarged solderable area of 0.015" x 0.020" as shown in Figure 2. Both changes are required to allow for the new plating process and should have minimal impact on form, fit or function.

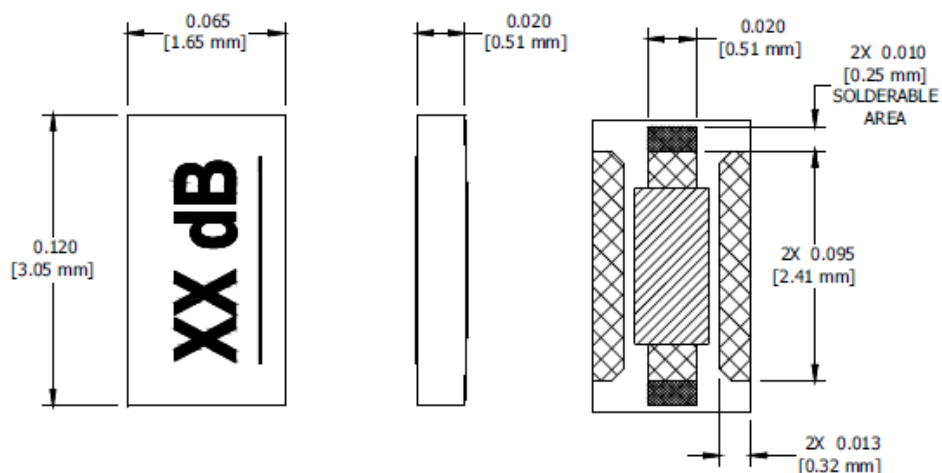


Figure 1 - KFA SMT Legacy Design



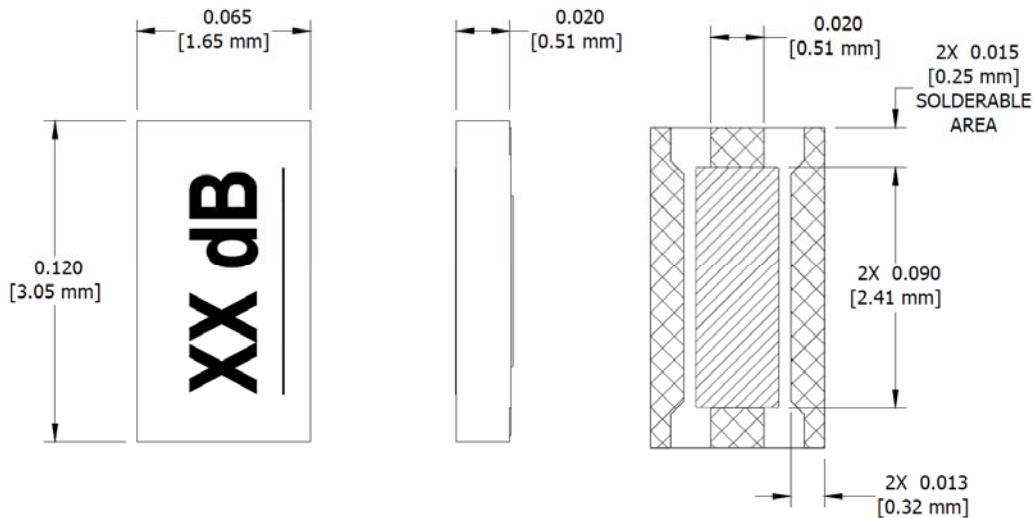


Figure 2 - KFA SMT Improved Design

### Reason for the Change:

Plating process improves solderability of units to printed circuit boards and many customers have requested this change from Smiths Interconnect.

### Effective Date:

As of October 31, 2018 the terminal change will be in place. Product will be delivered with plating after this date.

- For the KFAXX.XXSMT series
  - Revision – (dash) is the non-plated version and Revision A is the new plated version.
- For the KFAXX.XXSMTF series
  - Revision D is the non-plated version and Revision E is the new plated version.

### Availability of New Samples:

Available upon request after October 31, 2018

### For more information contact:

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